



반도체 테스트 부문
Total Solution Provider

INVESTOR RELATIONS JULY 2025

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Semiconductor Testing
Total Solution Provider



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Chapter 01 Company Introduction

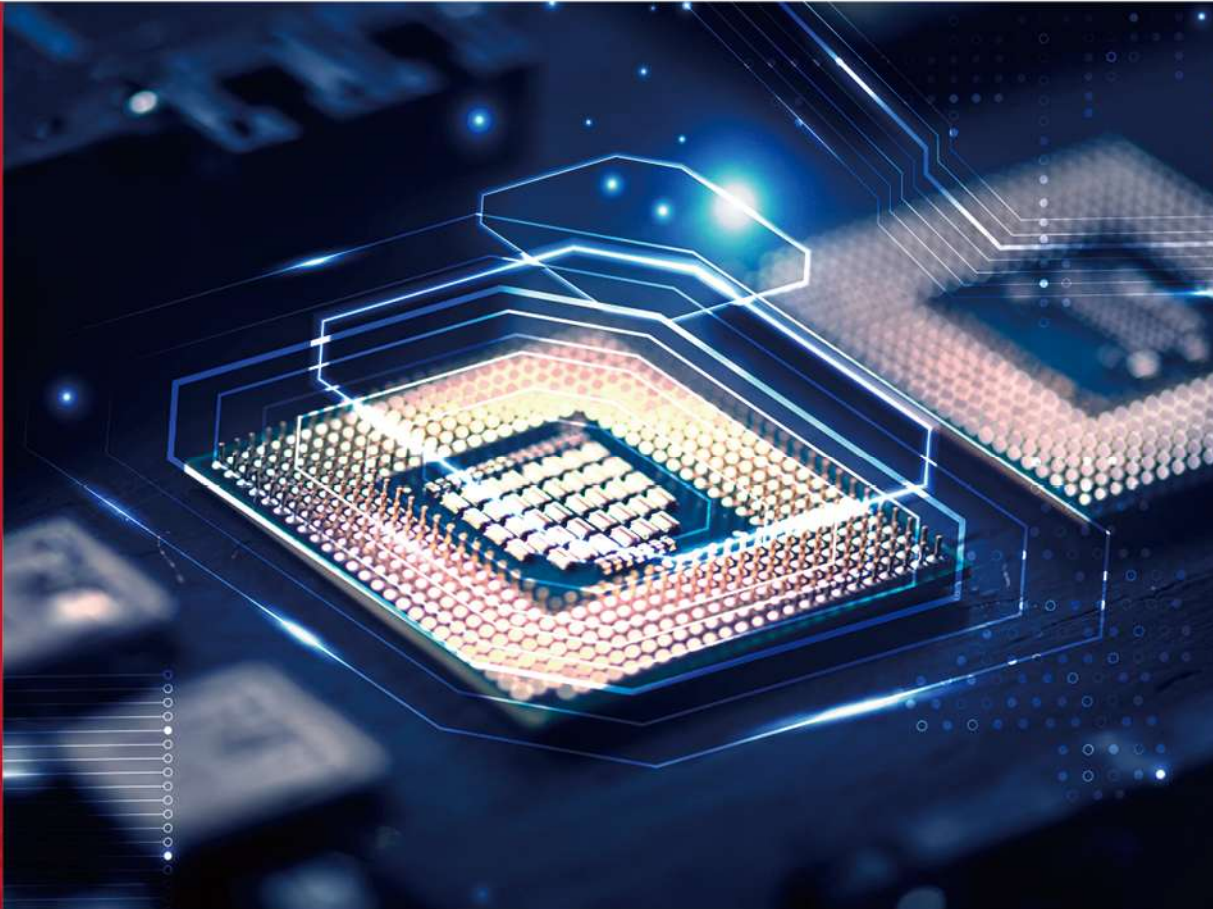
Chapter 02 Business Performance

Chapter 03 Growth Strategy

Appendix



Semiconductor Test
Total Solution Provider



01

**TFE,
Total Solution
Provider!**

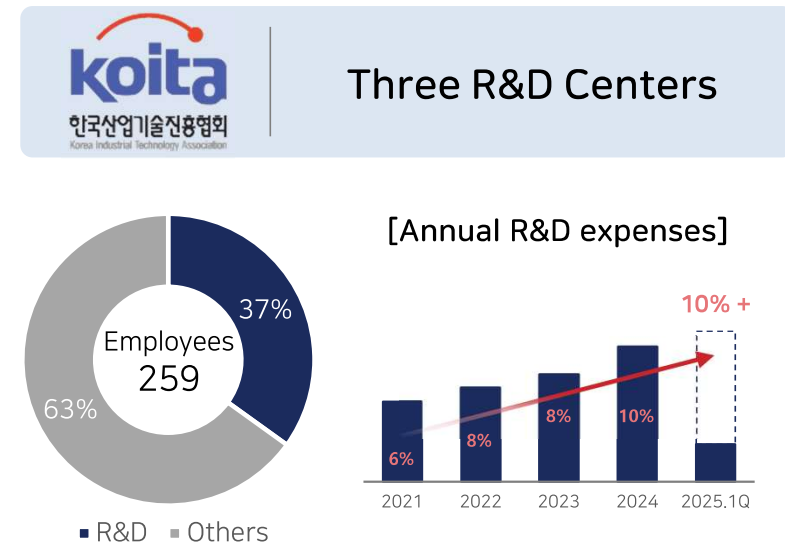
01 Company Overview

Total Solution Provider in Semiconductor Test Field

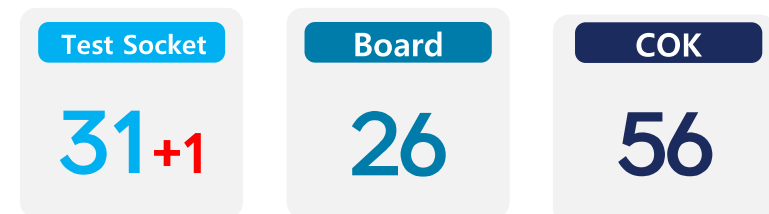
Company Overview

Company	TFE Co., Ltd
CEO	SJ. Moon
Establishment	2003. 10. 29
Capital	KRW 1.138 billion
Employees	259 (R&D 97)
Business Site	Gyeonggi-do, 18384, Republic of Korea
Website	www.tfe.co.kr

R&D Innovation Framework

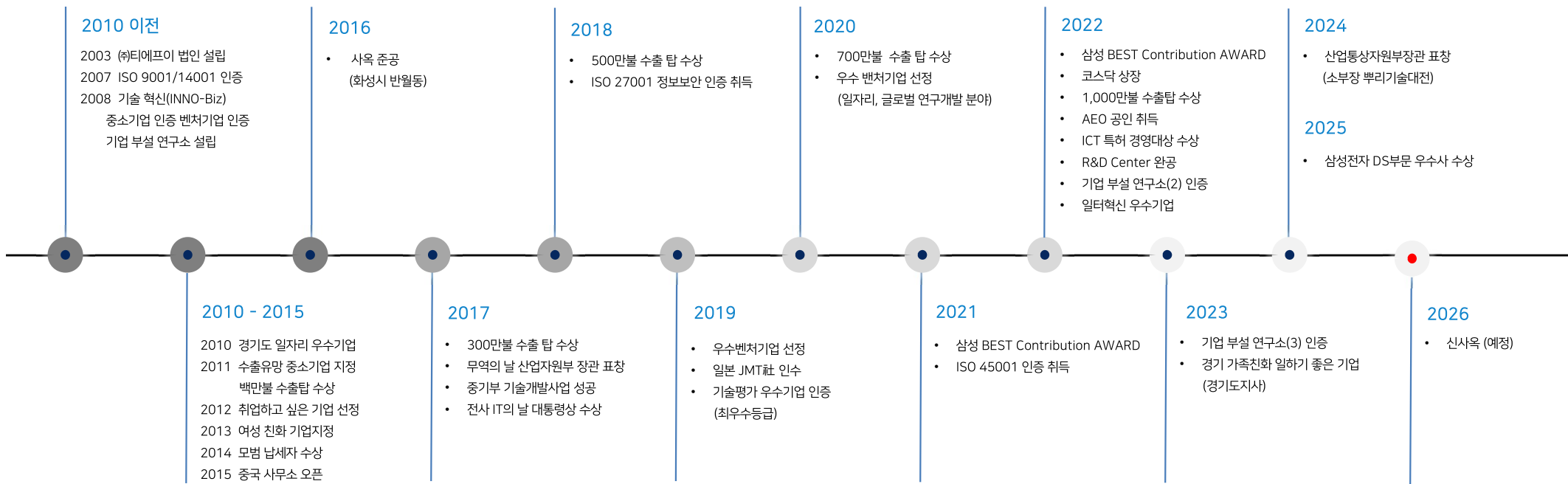


Patent and intellectual property status



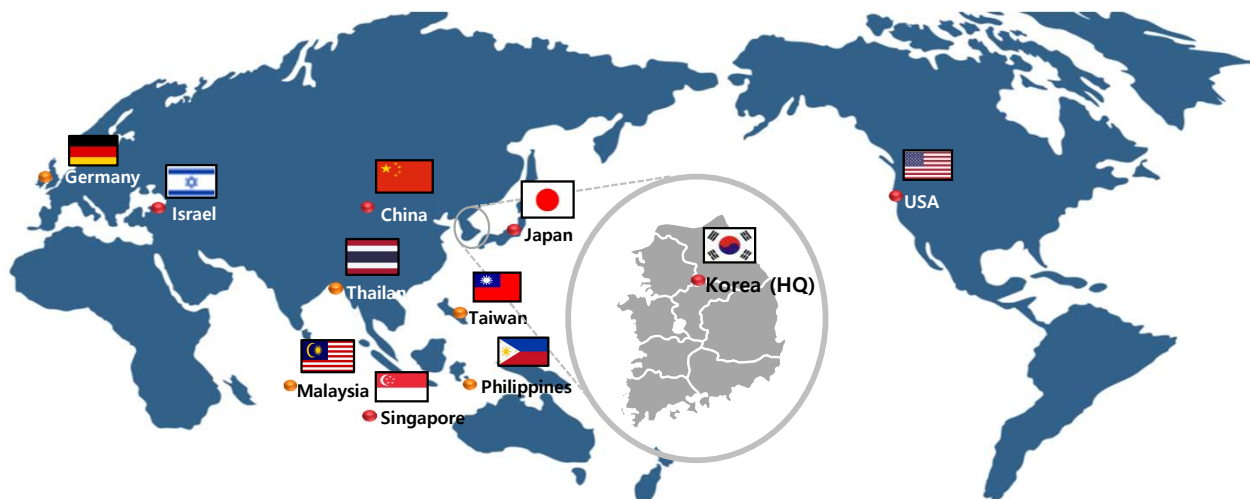
02 Corporate History

Proving Innovation, Sustaining Excellence



03 Infra – All over the World

Global Infrastructure, Local Commitment



- 01 Planning new branch in USA & Singapore
- ✓ Total 4 Local Staffs on duty
 - ✓ Actively targeting the USA & SG market, the headquarters of many global customers

- 02 Agency, a solid partners
- ✓ USA, Taiwan, Israel, Singapore, etc.
 - ✓ Continuous searching for partners

- 03 Exhibitions
- ✓ 4 exhibitions scheduled for 2025
 - ✓ TestConX(USA), Semi SEA(Singapore), Taiwan, USA, Japan

Hwaseong HQ



Hyangnam Factory



Dongtan Factory



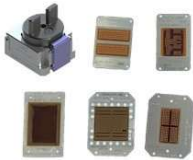
JMT (Japan)




04 Product Portfolio

One-Stop Solution for Global Chipmakers' Economic Benefits

Test Socket




[Memory]




[Non-Memory]

Electrical connection between test board and chip

Board



[Test Board]




[Burn-in Board]


Conduct electrical connection

High/Low temperature test

COK



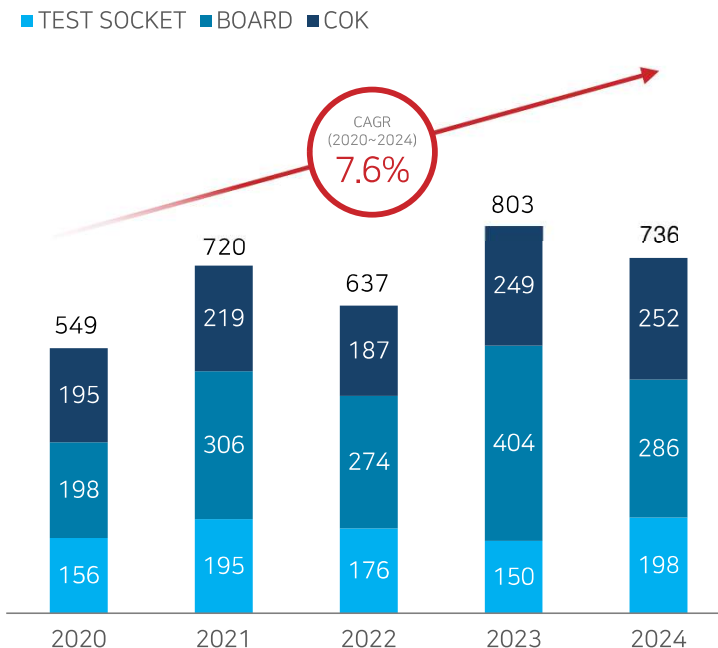
[Memory]



[Non-Memory]

Transfer chips & Support connectivity for inspection

Sales trends by Product (Unit: KRW 100 million)

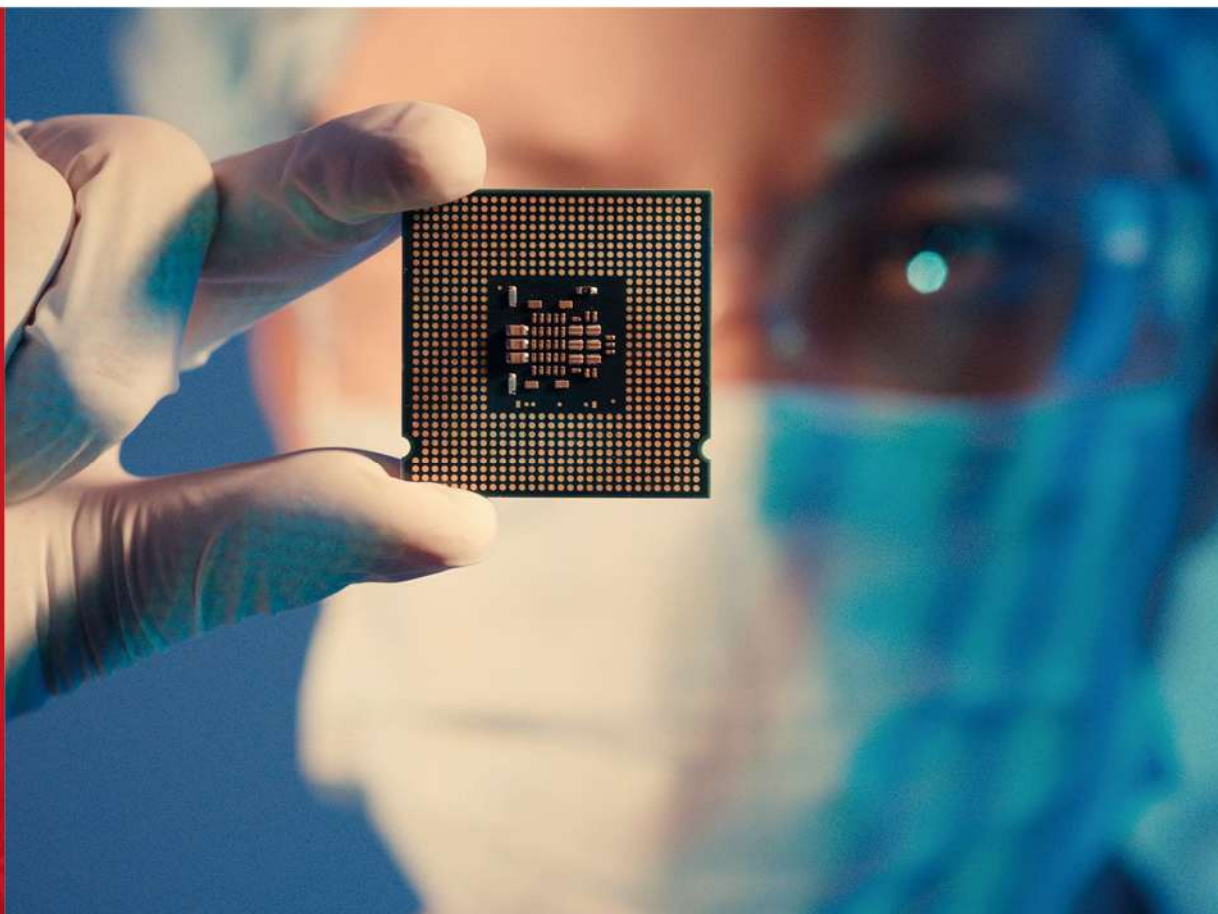


※ Consolidated Financial Statements Basis

3 : 4 : 3

02

Business Performance



Semiconductor Test
Total Solution Provider

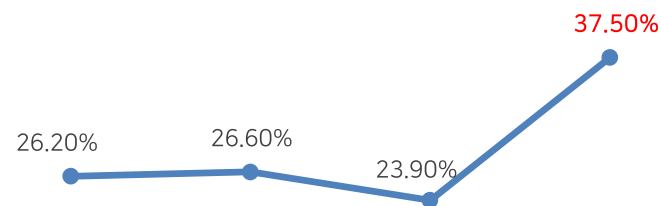
01 Business Performance

YoY 27%↑

2025. 1Q Sales **22.0** Billion won

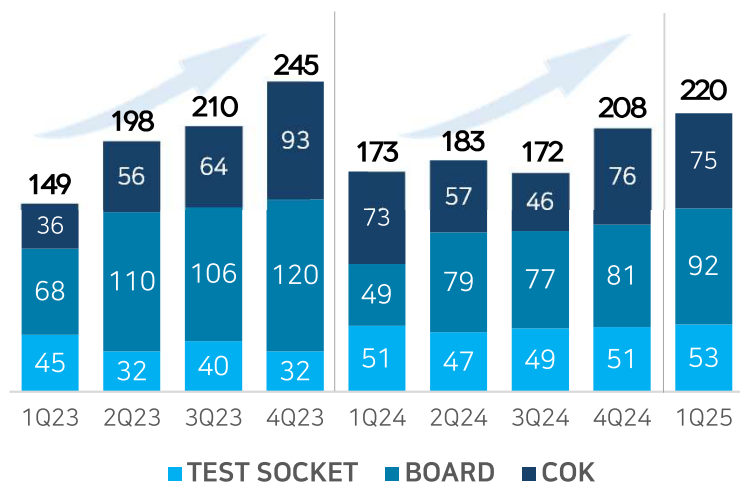
※Consolidated Financial Statements Basis

Export Revenue % (2022~2025.1Q)



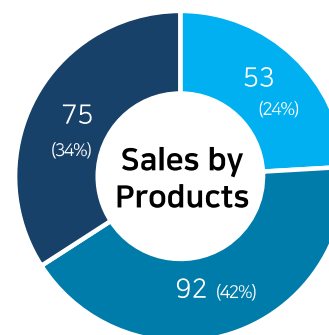
Quarterly Sales Status (2023~2025.1Q)

(Unit: KRW 100 million)

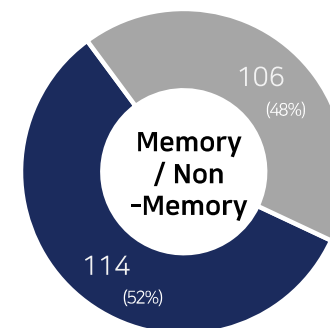


Sales Status by Products (2025.1Q)

(Unit: KRW 100 million)



■ TEST SOCKET ■ BOARD ■ COK



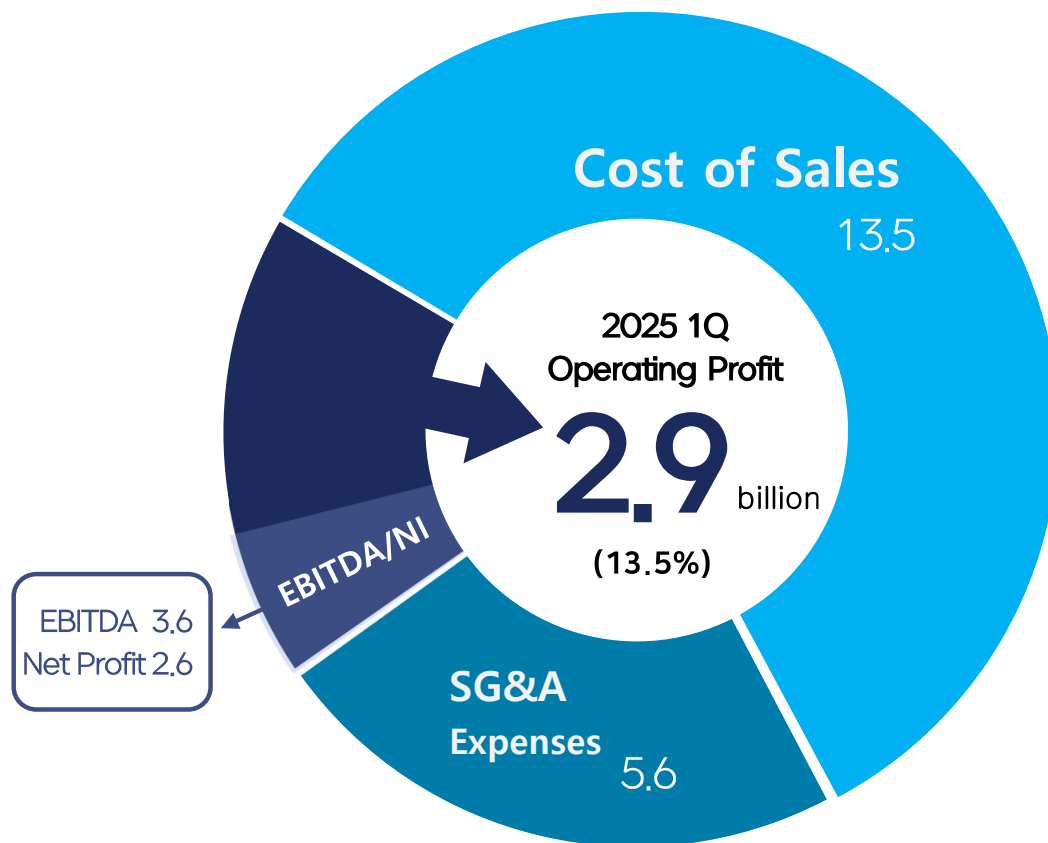
■ Memory ■ Non-Memory

02 Business Performance

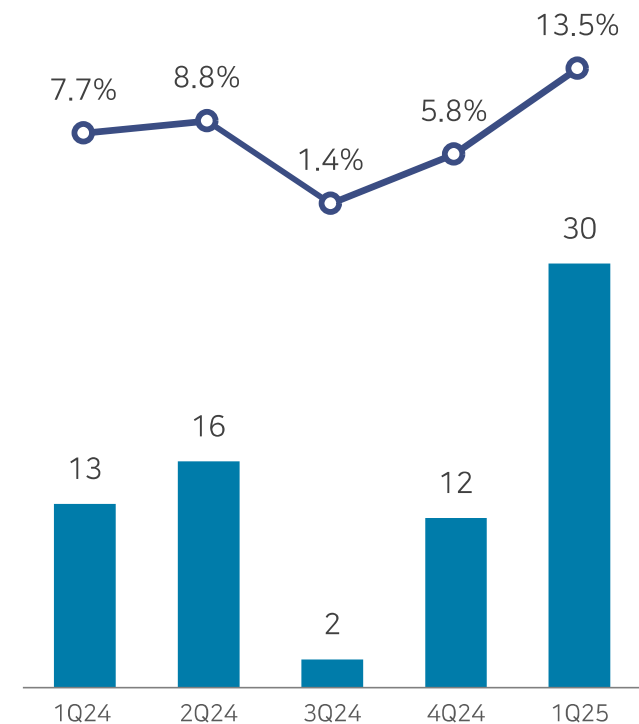
Solid Q1 Signals Another Promising Year

Quarterly Operating Profit Status (2024~2025.1Q)

(Unit: KRW 100 million, %)



※ Consolidated Financial Statements Basis



※ Consolidated Financial Statements Basis

03 Business Performance

Well-Capitalized and Ready to Scale

(단위: 억원)

Assets	1,316	Liabilities	504
유동자산	743	유동부채	169
현금성 자산 등	542	차입금	73
매출채권	87	비유동부채	335
⋮		전환사채	232
비유동자산	573	Equity	812
유형자산	461	자본금	11
⋮		자본잉여금 등	292
		⋮	
		이익잉여금	509

주요 경영지표

유동비율		부채비율	
24Y	25.1Q	24Y	25.1Q
468.5%	440.1%	61.6%	62.1%

당기순이익률		영업이익률	
24Y	25.1Q	24Y	25.1Q
2.0%	11.9%	6.0%	13.5%

- 24Y 전환사채평가 제외 시 당기순이익률 11.1%

Capex

(단위: 억원)

22Y	23Y	24Y	25.1Q
58	108	183	33

※ 연결 재무제표 기준

03

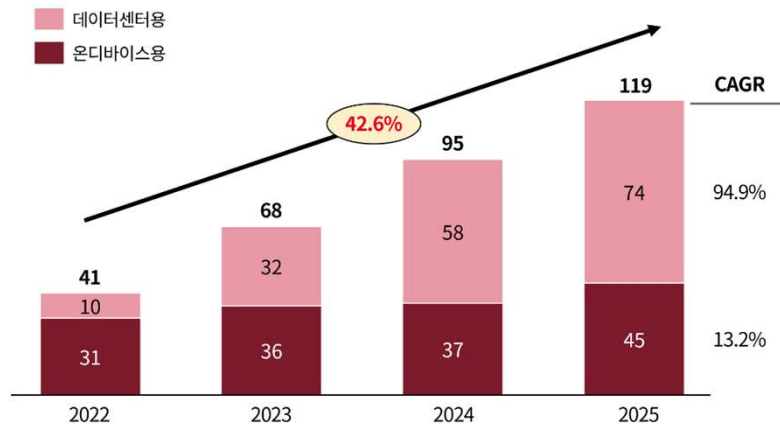
Growth Strategy



Semiconductor Test
Total Solution Provider

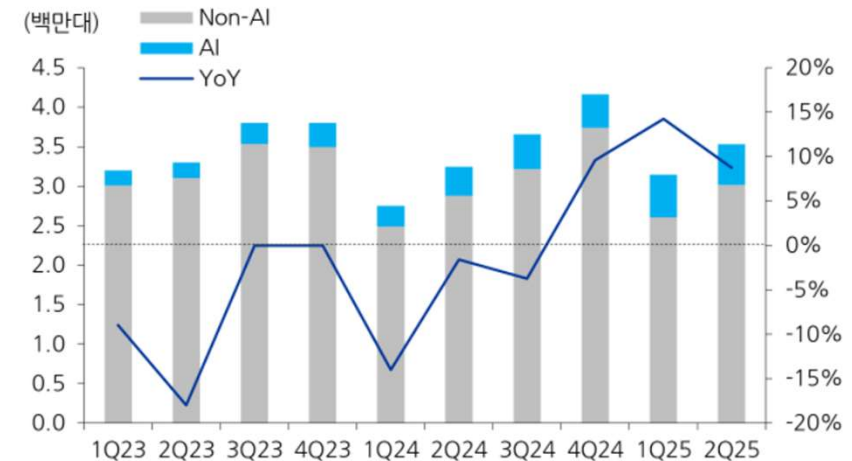
01 Market Insight

AI 반도체 시장 규모 변화 (단위: 십억 달러)



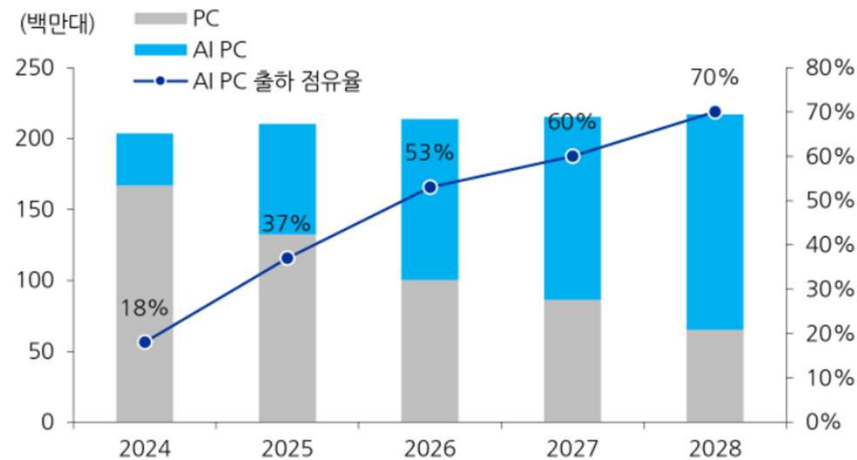
출처: Omdia, 한국수출입은행, PwC컨설팅 Insight April, 2025

서버 시장 전망과 YoY 추이



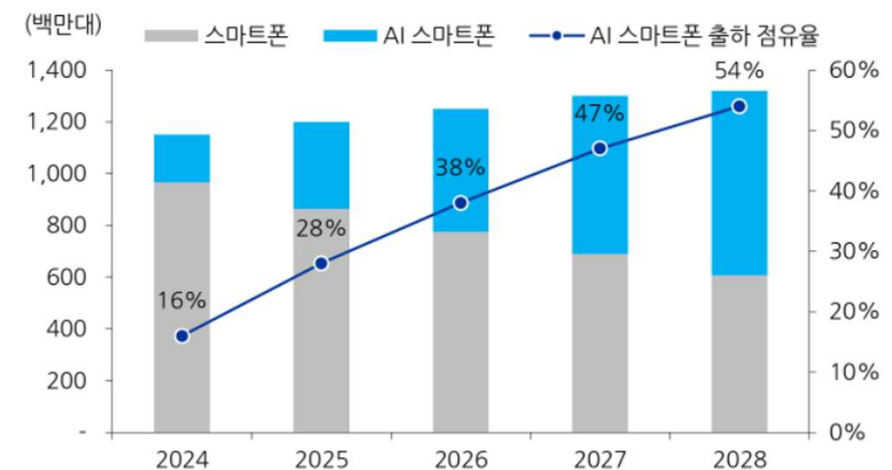
자료: 유진투자증권 추정치

데스크탑/노트북 출하량과 AI 제품 출하 점유율 전망



자료: 유진투자증권 추정치

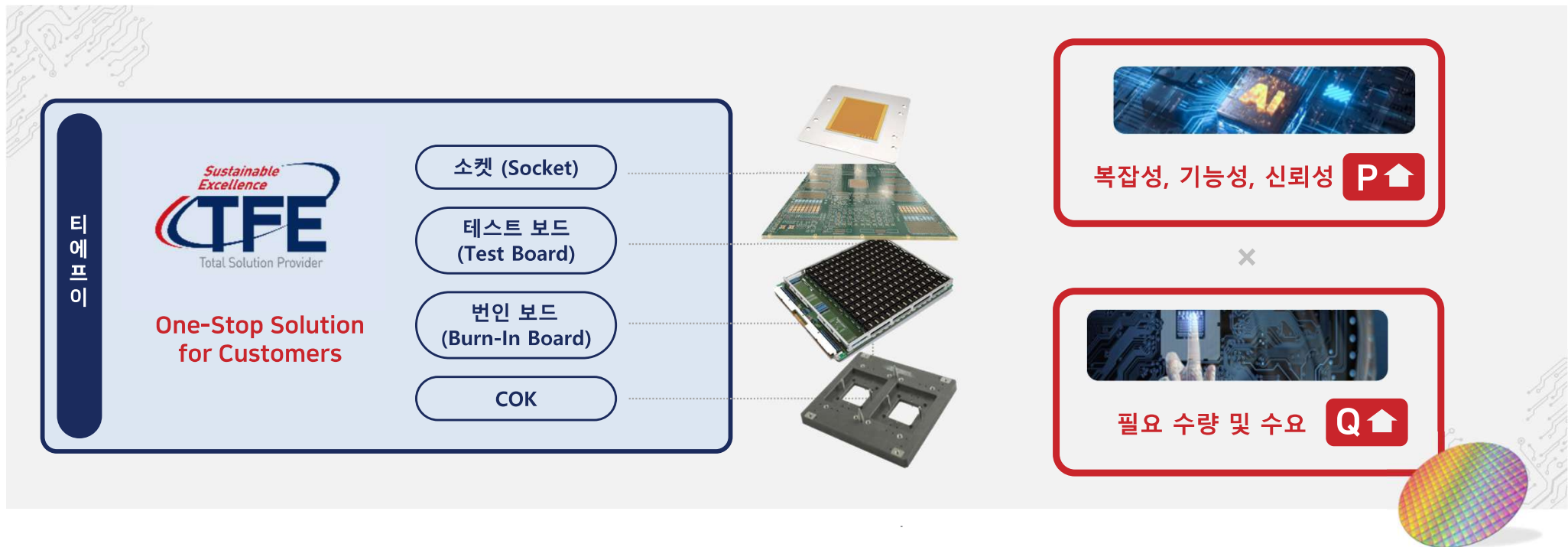
스마트폰 출하량과 AI 제품 출하 점유율 전망



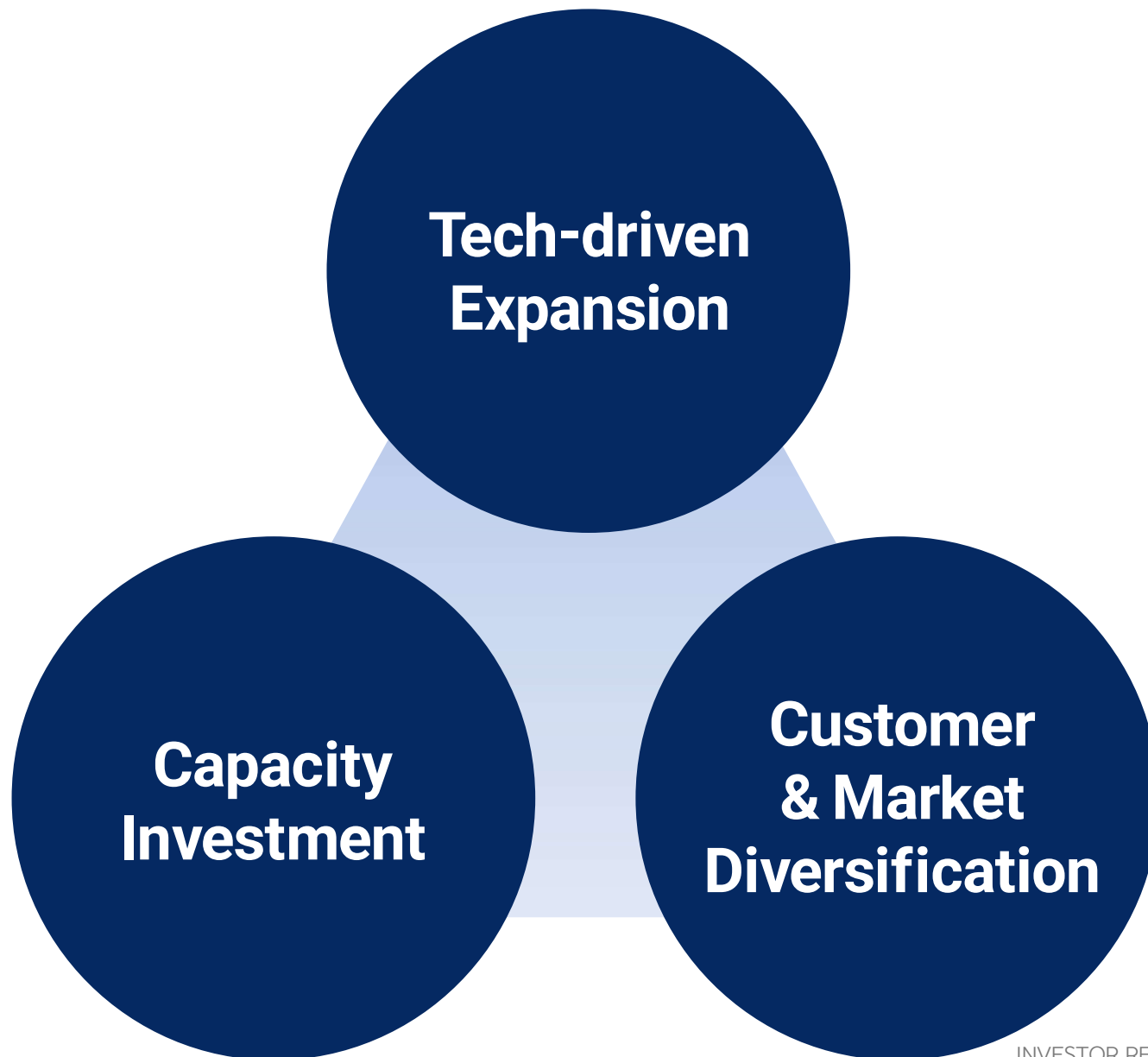
자료: 유진투자증권 추정치

02 One-Stop Solution - One & Only

Global No.1 Semiconductor Total Solution Provider



03 Growth Strategy – *Brave New World!*



04 Growth Strategy – *Brave New World!*

TFE, Driving the Future Test Solution

AI(HBM, 2.5D)



DDR5 Module



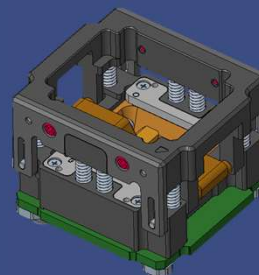
SOCAMM/LPCAMM
(Next-Generation
Module)



Flagship Smart
Phone AP



Burn-in
Test Socket



CXL
CPO
HBF
Glass Substrate,
Graphics Card

•
•

05 New Plant in 2026 – *Higher Capacity & Automation*

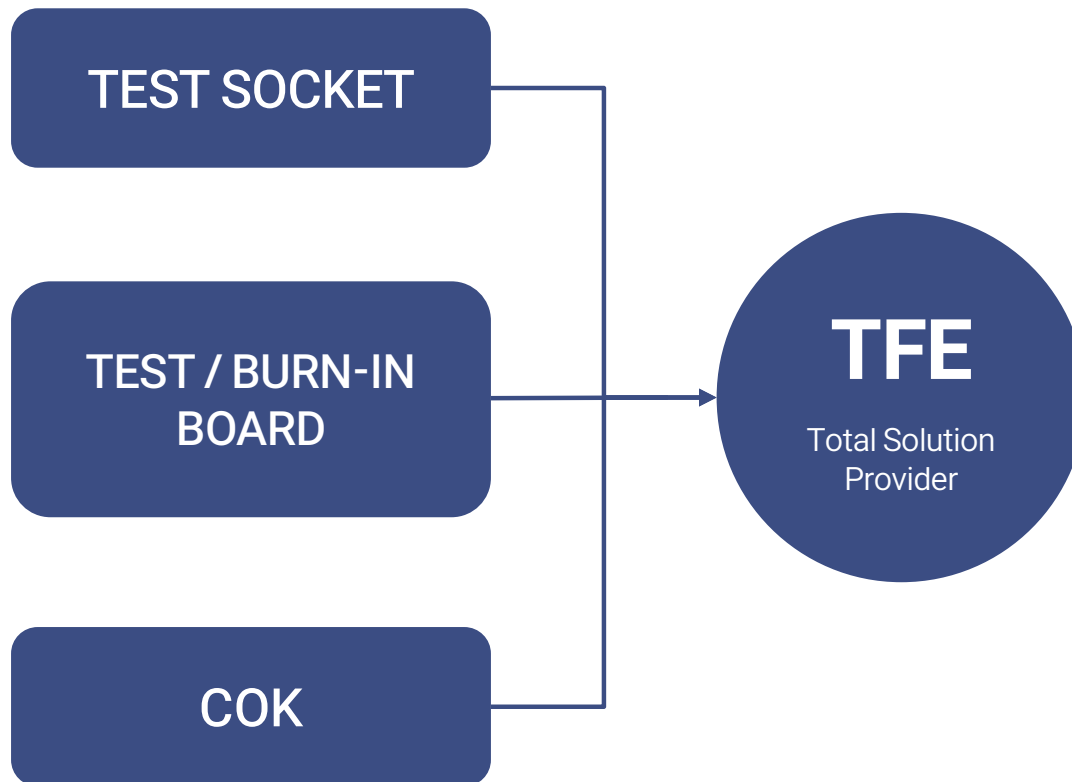


06 Our Vision

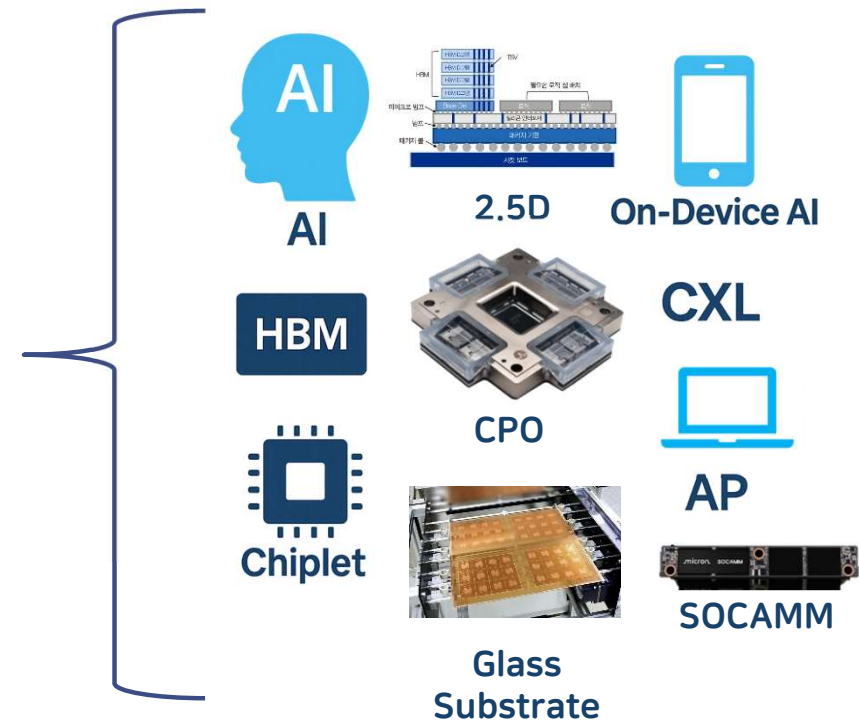
One & Only Test Partner for the Future



TEST COVERAGE



NEW-GEN TECHNOLOGIES





Appendix

01. Financial Statements Summary

01 Financial Statements Summary

요약 재무상태표

(단위: 억원)

구분	2025.1Q	2024	2023
유동자산	743	724	535
- 현금성자산	223	194	407
- 금융자산	319	372	-
- 채권·채고 등	201	158	128
비유동자산	573	543	379
자산총계	1,316	1,267	914
유동부채	169	155	144
비유동부채	335	328	58
※ 장단기차입금	75	76	68
부채총계	504	483	202
자본금	11	11	11
자본잉여금	241	240	240
기타자본항목	50	50	(8)
이익잉여금	510	483	469
자본총계	812	784	712

※ 연결 재무제표 기준

요약 손익계산서

(단위: 억원)

구분	2025.1Q	2024	2023
매출액	220	736	803
매출원가	135	503	536
매출총이익	85	233	267
판매관리비	55	189	175
영업이익	30	44	92
영업외수익	7	46	32
영업외비용	7	86	10
세전순이익	30	4	114
법인세비용	4	(11)	3
당기순이익	26	15	111